8-Bit Static Shift Register

The MC14014B and MC14021B 8-bit static shift registers are constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These shift registers find primary use in parallel-to-serial data conversion, synchronous and asynchronous parallel input, serial output data queueing; and other general purpose register applications requiring low power and/or high noise immunity.

Features

- Synchronous Parallel Input/Serial Output (MC14014B)
- Asynchronous Parallel Input/Serial Output (MC14021B)
- Synchronous Serial Input/Serial Output
- Full Static Operation
- "Q" Outputs from Sixth, Seventh, and Eighth Stages
- Double Diode Input Protection
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- MC14014B Pin-for-Pin Replacement for CD4014B
- MC14021B Pin-for-Pin Replacement for CD4021B
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	٧
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8-Second Soldering)	260	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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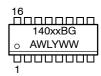
MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648 16<u>ቤ ሉ ሉ ሉ ሉ ሉ ሉ ለ</u> MC140xxBCP o AWLYYWWG 1 ፑፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ ፑ

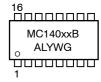


SOIC-16 D SUFFIX CASE 751B





SOEIAJ-16 F SUFFIX CASE 966



x = Specific Device Code A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G = Pb-Free Indicator

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

TRUTH TABLE

SERIAL OPERATION:

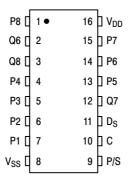
t	Clock	Ds	P/S	Q6 t=n+6	Q7 t=n+7	Q8 t=n+8
n	\	0	0	0	?	?
n+1		1	0	1	0	?
n+2		0	0	0	1	0
n+3		1	0	1	0	1
	~	Х	0	Q6	Q7	Q8

PARALLEL OPERATION:

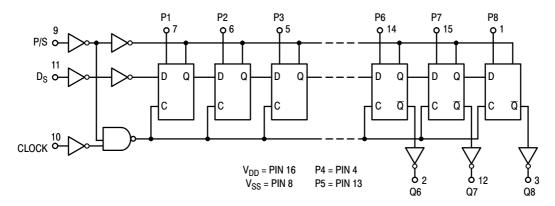
CI					
MC14014B MC14021B		Ds	P/S	Pn	*Q _n
	Х	Х	1	0	0
	Х	Х	1	1	1

*Q6, Q7, & Q8 are available externally X = Don't Care

PIN ASSIGNMENT



LOGIC DIAGRAM



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

				- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	V _{DD} Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
$V_{in} = 0$ or V_{DD}	"1" Level	V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	"0" Level	V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current $(V_{OH} = 2.5 \text{ Vdc})$ $(V_{OH} = 4.6 \text{ Vdc})$ $(V_{OH} = 9.5 \text{ Vdc})$ $(V_{OH} = 13.5 \text{ Vdc})$	Source	I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - -	- 1.7 - 0.36 - 0.9 - 2.4	- - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current		l _{in}	15	_	± 0.1	-	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	-	-	_	_	5.0	7.5	-	_	pF
Quiescent Current (Per Package)		I _{DD}	5.0 10 15	- - -	5.0 10 15	- - -	0.005 0.010 0.015	5.0 10 15	- - -	150 300 600	μAdc
Total Supply Current (Note (Dynamic plus Quiesce Per Package) (C _L = 50 pF on all outp buffers switching)	ent,	I _T	5.0 10 15			$I_T = (1$.75 μA/kHz) .50 μA/kHz) .25 μA/kHz)	f + I _{DD}			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.0015.

SWITCHING CHARACTERISTICS (Note 5) (C $_L$ = 50 pF, T_A = 25 $^{\circ}C)$

Characteristic	Symbol	V _{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time	t _{TLH} ,					ns
t _{TLH} , t _{THL} = (1.5 ns/pF) C _L + 25 ns	t _{THL}	5.0	_	100	200	
t_{TLH} , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$	1112	10	-	50	100	
t_{TLH} , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$		15	_	40	80	
Propagation Delay Time (Clock to Q, P/S to Q)	t _{PLH} ,					ns
t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 315 \text{ ns}$	t _{PHL}	5.0	_	400	800	
t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 137 \text{ ns}$		10	_	170	340	
t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 90 \text{ ns}$		15	_	115	230	
Clock Pulse Width	t _{WH}	5.0	400	150	_	ns
	****	10	175	75	-	
		15	135	40	_	
Clock Frequency	f _{cl}	5.0	_	3.0	1.5	MHz
		10	_	6.0	3.0	
		15	_	8.0	4.0	
Parallel/Serial Control Pulse Width	t _{WH}	5.0	400	150	_	ns
		10	175	75	_	
		15	135	40	_	
Setup Time	t _{su}	5.0	200	100	-	ns
P/S to Clock		10	100	50	-	
		15	80	40	_	
Hold Time	t _h	5.0	20	- 2.5	-	ns
Clock to P/S		10	20	- 10	-	
		15	25	0	_	
Setup Time	t _{su}	5.0	350	150	-	ns
Data (Parallel or Serial) to		10	80	50	-	
Clock or P/S		15	60	30	_	
Hold Time	t _h	5.0	45	0	_	ns
Clock to D _s		10	35	0	_	
		15	35	5	_	
Hold Time	t _h	5.0	50	25	_	ns
Clock to P _n		10	45	20	-	1
		15	45	20	_	
Input Clock Rise Time	t _{r(cl)}	5.0	-	-	15	μs
		10	_	_	5	
		15	_	_	4	

^{5.} The formulas given are for the typical characteristics only at 25°C.
6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

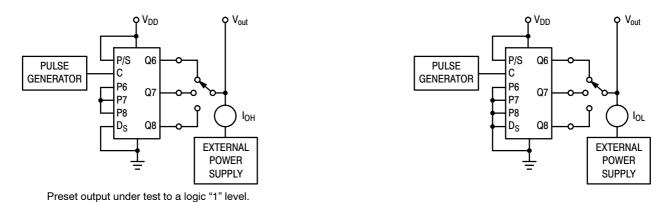


Figure 1. Output Source Current Test Circuit

Figure 2. Output Sink Current Test Circuit

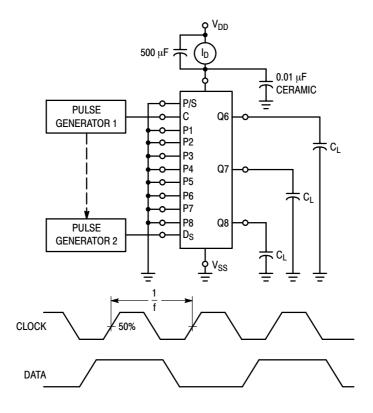


Figure 3. Power Dissipation Test Circuit and Waveform

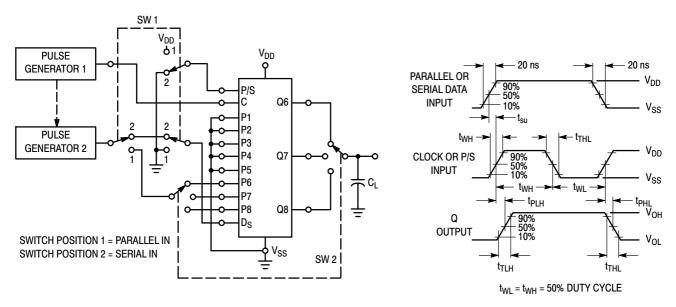


Figure 4. Switching Time Test Circuit and Waveforms

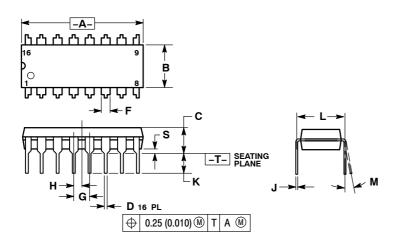
ORDERING INFORMATION

Device	Package	Shipping [†]
MC14014BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14014BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14014BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14014BFELG	SOEIAJ-16	2000 Units / Tape & Reel
MC14021BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14021BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14021BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14021BFELG	SOEIAJ-16	2000 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 **ISSUE T**



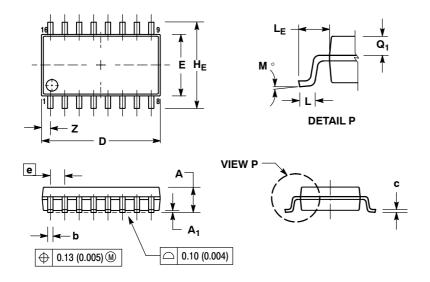
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. 3.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
М	0°	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01

ISSUE A



NOTES:

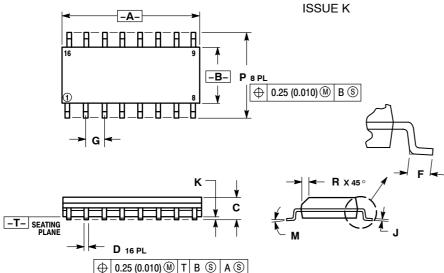
- DIMENSIONING AND TOLERANCING PER ANSI
- 714.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 THE LEAD WIDTH DIMENSION (b) DOES NOT
- INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) DAMBAR PHOTOSONS STREET BY USE OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	-	2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050	BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

SOIC-16 D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05

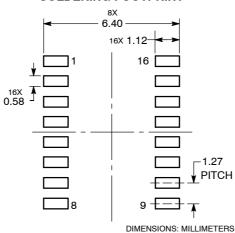


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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